(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
25 October 2001 (25.10.2001)

PCT

(10) International Publication Number
WO 01/80303 A3

(51) International Patent Classification[7]: H01L 21/60

(21) International Application Number: PCT/US01/11319

(22) International Filing Date: 6 April 2001 (06.04.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/551,312 18 April 2000 (18.04.2000) US

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(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW.

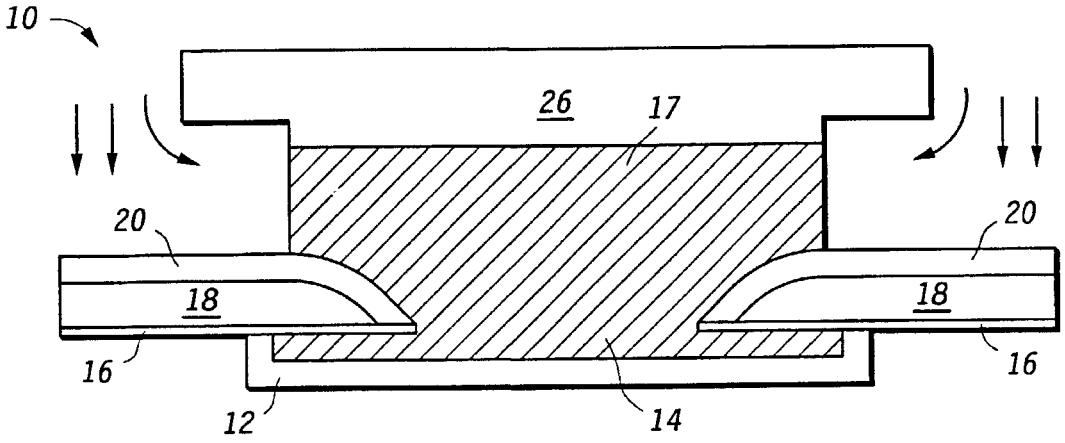
(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

(88) Date of publication of the international search report:
21 February 2002

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD AND APPARATUS FOR MANUFACTURING AN INTERCONNECT STRUCTURE



(57) Abstract: An interconnect structure (10), such as a flip-chip structure, including a base pad (14) and a stud (17) formed on the base pad (14) and extending from the base pad (14) is disclosed. The stud (17) and base pad (14) are formed to be continuous and of substantially the same electrically conductive base material. Typically, a solder structure (26) is formed on the stud (17) wherein the solder structure (26) is exposed for subsequent reflow attachment to another structure. The present invention relates to packaging integrated circuits, more particularly to the structure and processing of a stud (17) and bump without the standard under bump metallurgy.

WO 01/80303 A3